Final Product Change Notification | 201712013F01

Issue Date: 20-Jun-2019
Effective Date: 18-Sep-2019
Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.
For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

Management Summary

Assembly transfer of FXOS8700CQ product from Amkor Korea (ATK1) site to ASE-ChungLi Taiwan (ASECL) site for continuous customer supply. Includes ASIC design fix to allow multipoint SPI communication.

Change Category

[ ] Wafer Fab Process	[X] Assembly Process	[ ] Product Marking	[ ] Test Location	[X] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[X] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[X] Other - Removal of the previous SPI errata.			

FXOS8700CQ ASECL Assembly Transfer with Copper Bond Wire Qualification

Description of Change

NXP Semiconductors announces the assembly transfer of the FXOS8700CQ product from Amkor Korea (ATK1) site to ASE-ChungLi Taiwan (ASECL) site. This product was qualified with a material change from Gold (Au) bond wire, Sumitomo EME-G700 mold compound, Henkel ATB-125 die attach film, and LGI (STW) Roughened PPF (micro NiPdAuAg) leadframe to Gold Palladium Copper (AuPdCu) bond wire, Sumitomo EME-G700LA version P mold compound, Ablestik ATB-F125 and Ablestik ATB125HA2 die attach films, and Shinko Roughened Copper, Tin Plated (CuSn) leadframe. This assembly transfer also includes the ASIC design fix to allow multipoint SPI communication.

Reason for Change
The assembly transfer to ASECL is for supply continuity as a result of ATK1 site closure. The change from Gold to Gold Palladium Copper bond wire is to align with industry standards for bond wire material type. The change of the mold compound and die attach material is to standardize the bill of materials at the ASECL assembly site. This change also removes the errata to allow multipoint SPI communication.
Identification of Affected Products
Product identification does not change
There is no change to the orderable part numbers. NXP will have traceability of the assembly site by the 1st and 2nd digit of the tracecode.

Product Availability

Sample Information
Samples are available upon request
Production
Planned first shipment 16-Sep-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
This change also removes the errata to allow multipoint SPI communication.
Data Sheet Revision
A new datasheet will be issued
Disposition of Old Products
Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file
Self qualification: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 20-Jul-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Michelle Kelsey
Position Product Line Manager
e-mail address michelle.kelsey@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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